

Fair-Rite P/N 2512065007Y3

Y Chip Bead Material Grade

Nominal Chemical Composition

Supporting notes:

1. P/N 2512065007Y3 consists of:
 - a core Y Chip Bead Material Grade
 - b Termination Plating SnNiAg
2. Moisture Sensitivity Level (MSL)= 1
3. Max Reflow Temp= 260 degC
4. Max Time at Max Reflow Temp= 40 sec
5. RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
6. RoHS Conversion Date= 1/1/2005
7. RoHS Compliance Marking is Contained on Shipping Labels

| <u>Ferrite -Compound</u> | <u>CAS Number</u> | <u>wt %</u> | Wt of core (g)= | |
|--------------------------|-------------------|-------------|-----------------|---|
| | | | 0.024 | |
| Fe2O3 | 1309-37-1 | 65 | 0.0156 | Compound Weight (g) Breakdown of Y Chip Bead Material Grade |
| ZnO | 1314-13-2 | 17 | 0.0041 | |
| NiO | 1313-99-1 | 9 | 0.0022 | |
| CuO | 1317-38-0 | 6 | 0.0014 | |
| MnO | 1344-43-0 | 3 | 0.0007 | |

| <u>Termination Plating - Elements</u> | <u>CAS Number</u> | <u>wt %</u> | Wt of termination (g)= | |
|---|-------------------|-------------|------------------------|--|
| | | | 0.006 | |
| Sn | 7440-31-5 | 14.3 | 0.00086 | Element Weight (g) Breakdown of Pb- Free Termination Plating |
| Ni | 7440-02-0 | 6.9 | 0.00041 | |
| Ag | 7440-22-4 | 78.8 | 0.00473 | |

Calculated Maximum Levels of RoHS Restricted Substances Present in Y Chip Bead Material Grade

| <u>Impurity Substance</u> | <u>RoHS Threshold (ppm):</u> | <u>ppm</u> | Wt of core (g)= | |
|-------------------------------|----------------------------------|------------|-----------------|---|
| | | | 0.024 | |
| Cr+6 | 1000 | 0.00 | 0 | RoHS Impurity Substance Weight (g) Breakdown of Y Chip Bead Material Grade |
| Cd | 100 | 0.00 | 0 | |
| Hg | 1000 | 0.00 | 0 | |
| Pb | 1000 | 0.00 | 0 | |
| PBB | 1000 | 0.00 | 0 | |
| PBDE | 1000 | 0.00 | 0 | |